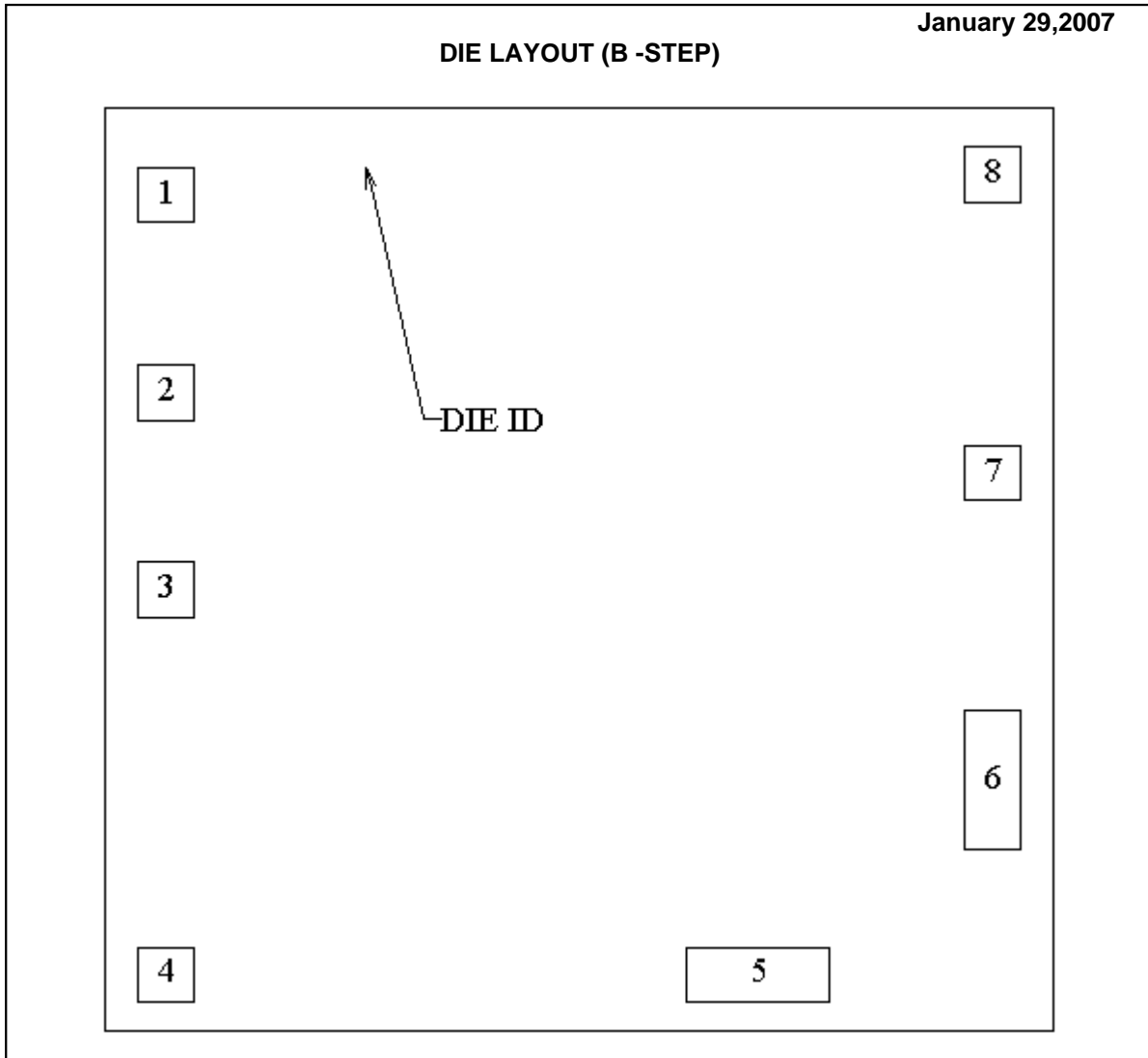


**LM3578A MDC MWC
SWITCHING REGULATOR**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1578B	Bond Pad Opening Size (min)	117 μ m x 117 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	2007 μ m x 1956 μ m 79.0mils x 77.0mils	Back Side Connection	Floating
Thickness	254 μ m Nominal		
Min Pitch	417 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT -	1	-874	793	117	x	117
INPUT +	2	-874	374	117	x	117
OSC	3	-874	-42	117	x	117
GND	4	-874	-858	117	x	117
EMITTER	5	379	-858	300	x	117
COLLECTOR	6	874	-446	117	x	296
CURRENT LIMIT	7	874	205	117	x	117
VIN	8	874	836	117	x	117

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